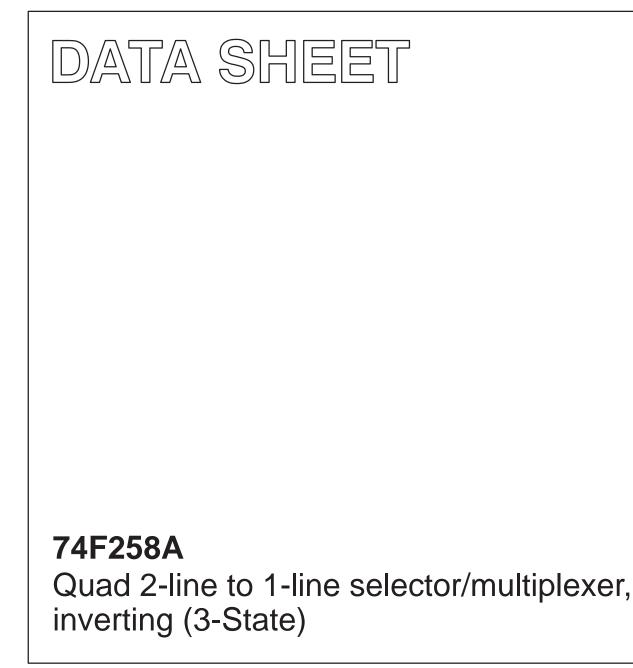
INTEGRATED CIRCUITS



Product specification IC15 Data Handbook 1996 Jan 05



Philips Semiconductors

74F258A

FEATURES

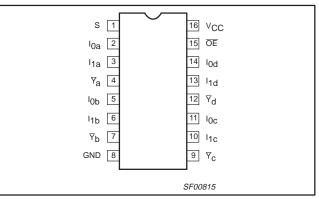
- Multifunction capability
- Non-inverting data path
- 3-State outputs
- See 74F257A for non-inverting version

DESCRIPTION

The 74F258A has four identical 2-input multiplexers with 3-State outputs which select 4 bits of data from two sources under control of a common Select (S) input. The I_{0n} inputs are selected when the Select input is Low and the I_{1n} inputs are selected when the Select input is High. Data appears at the outputs in inverted form.

The 74F258A is the logical implementation of a 4-pole, 2-position switch where the position of the switch is determined by the logic level supplied to the Select input. Outputs are forced to a High impedance "off" state when the Output Enable input (\overline{OE}) is High. All but one device must be in the High impedance state to avoid currents that would exceed the maximum ratings if outputs are tied together. Design of the output signals must ensure that there is no overlap when outputs of 3-State devices are tied together.

PIN CONFIGURATION



ТҮРЕ	TYPICAL PROPAGATION DELAY TYPICAL SUPF CURRENT (TOT	
74F258A	3.5ns	14mA

ORDERING INFORMATION

	ORDER CODE		
DESCRIPTION	COMMERCIAL RANGE V _{CC} = 5V ±10%, T _{amb} = 0°C to +70°C	PKG. DWG. #	
16-pin plastic DIP	N74F258AN	SOT38-4	
16-pin plastic SO	N74F258AD	SOT109-1	

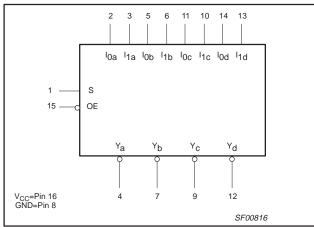
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
I _{0n} , I _{1n}	Data inputs	1.0/1.0	20µA/0.6mA
S	Common select input	1.0/1.0	20µA/0.6mA
ŌĒ	Output Enable input (active Low)	1.0/1.0	20µA/0.6mA
$\overline{Y}_a - \overline{Y}_d$	Data outputs	150/40	3.0mA/24mA

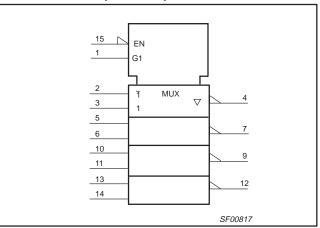
NOTE:

One (1.0) FAST Unit Load is defined as: 20µA in the High state and 0.6mA in the Low state.

LOGIC SYMBOL

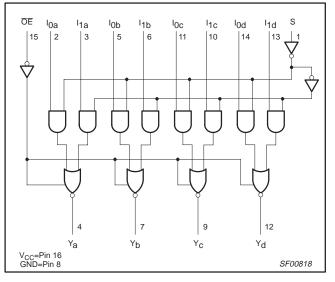


LOGIC SYMBOL (IEEE/IEC)



74F258A

LOGIC DIAGRAM



FUNCTION TABLE

	OUTPUT			
OE	S	I ₀	I ₁	Ÿ
Н	Х	Х	Х	Z
L	н	Х	L	Н
L	н	Х	н	L
L	L	L	Х	Н
L L	L	н	Х	L

H = High voltage level L = Low voltage level

X = Don't careZ = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in High output state	–0.5 to V_{CC}	V
I _{OUT}	Current applied to output in Low output state	48	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		LIMITS			
STWBOL		MIN	NOM	MAX	UNIT	
V _{CC}	Supply voltage	4.5	5.0	5.5	V	
V _{IH}	High-level input voltage	2.0			V	
VIL	Low-level input voltage			0.8	V	
I _{IK}	Input clamp current			-18	mA	
I _{ОН}	High-level output current			-3	mA	
I _{OL}	Low-level output current			24	mA	
T _{amb}	Operating free-air temperature range	0		70	°C	

74F258A

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	SYMBOL PARAMETER		TEST CONDITIONS ¹			LIMITS			UNIT
STWDUL						MIN	TYP ²	MAX	UNIT
V _{OH}	High-level output voltage		$V_{CC} = MIN, V$	ΊL = MAX,	±10%V _{CC}	2.4			V
			V _{IH} = MIN, I _O	L = MAX	±5%V _{CC}	2.7	3.3		V
V _{OL}	Low-level output voltage		V _{CC} = MIN, V	ΊL = MAX,	±10%V _{CC}		0.30	0.50	V
			V _{IH} = MIN, I _O	L = MAX	±5%V _{CC}		0.35	0.50	V
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$				-0.73	-1.2	V
l _l	Input current at maximum input voltage		$V_{CC} = MAX, V_I = 7.0V$					100	μA
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$					20	μΑ
۱ _{IL}	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$					-0.6	mA
I _{OZH}	Off-state output current, High-level voltage	applied	$V_{CC} = MAX, V_O = 2.7V$					50	μA
I _{OZL}	Off-state output current, High-level voltage	applied	$V_{CC} = MAX, V_O = 0.5V$					-50	μA
I _{OS}	Short-circuit output current ³		V _{CC} = MAX			-60		-150	mA
		I _{CCH}		I _{1n} =4.5V, OE=I ₀	_n =S=GND		8.5	11.5	mA
I _{CC}	Supply current (total)		$V_{CC} = MAX$	I _{1n} =S=4.5V, OE	=I _{0n} =GND		17	23	mA
			I _{1n} =OE=4.5V,I _{0n}		=S=GND		16	22	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

2. All typical values are at V_{CC} = 5V, T_{amb} = 25°C.

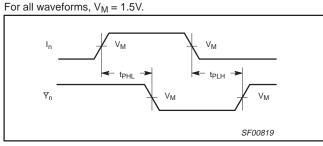
3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of High-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

AC ELECTRICAL CHARACTERISTICS

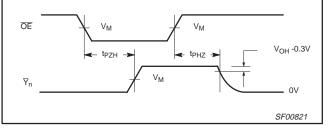
				LIMITS				
SYMBOL	PARAMETER	TEST CONDITIONS	$T_{amb} = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_{L} = 50pF, R_{L} = 500\Omega$			T _{amb} = -55° V _{CC} = +5. C _L = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay I_n to \overline{Y}_n	Waveform 1	3.0 1.0	4.5 2.5	6.0 4.0	2.5 1.0	7.0 4.5	ns ns
t _{PLH} t _{PHL}	Propagation delay S to \overline{Y}_n	Waveform 2	3.5 2.5	6.5 6.0	8.0 8.0	3.5 2.5	9.0 9.0	ns ns
t _{PZH} t _{PZL}	Output enable time to High or Low level	Waveform 3 Waveform 4	4.0 4.0	6.0 5.5	7.5 7.5	3.5 3.5	8.5 8.5	ns ns
t _{PHZ} t _{PLZ}	Output disable time from High or Low level	Waveform 3 Waveform 4	2.0 2.0	3.5 3.5	5.5 5.5	2.0 2.0	6.5 6.0	ns ns

74F258A

AC WAVEFORMS

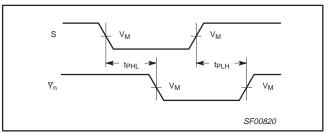


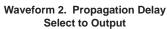


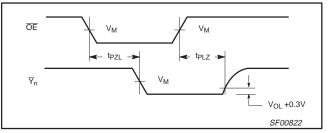


Waveform 3. 3-State Output Enable Time to High Level and Output Disable Time from High Level

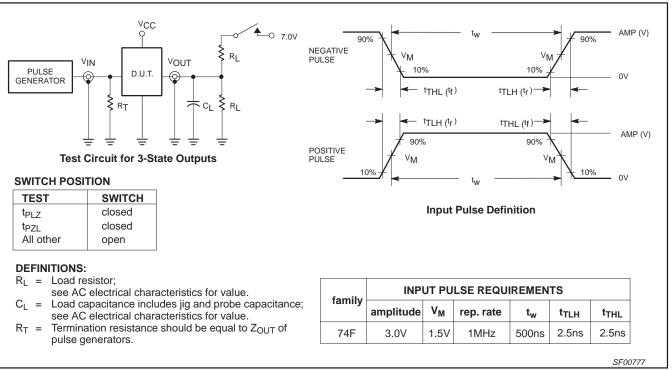
TEST CIRCUIT AND WAVEFORM



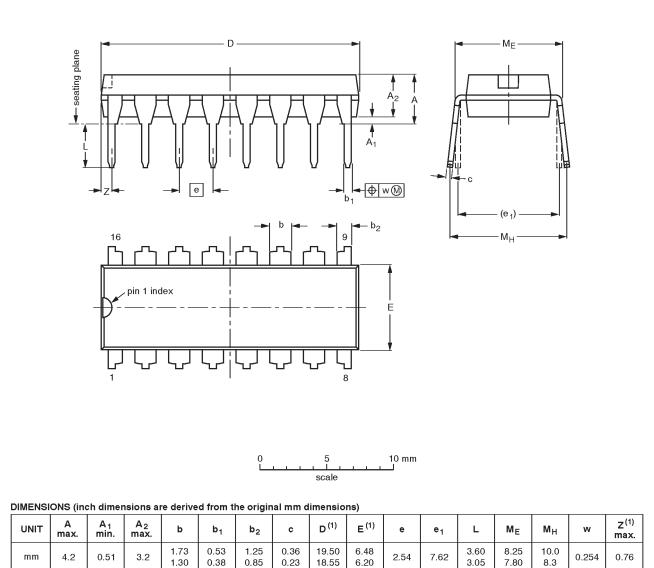




Waveform 4. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level



DIP16: plastic dual in-line package; 16 leads (300 mil)



inches

0.17

0.020

0.13

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

0.068

0.051

0.021

0.015

0.049

0.033

0.014

0.009

OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT38-4						-92-11-17- 95-01-14

0.77

0.73

0.26

0.24

0.10

0.30

0.14

0.12

0.32

0.31

0.39

0.33

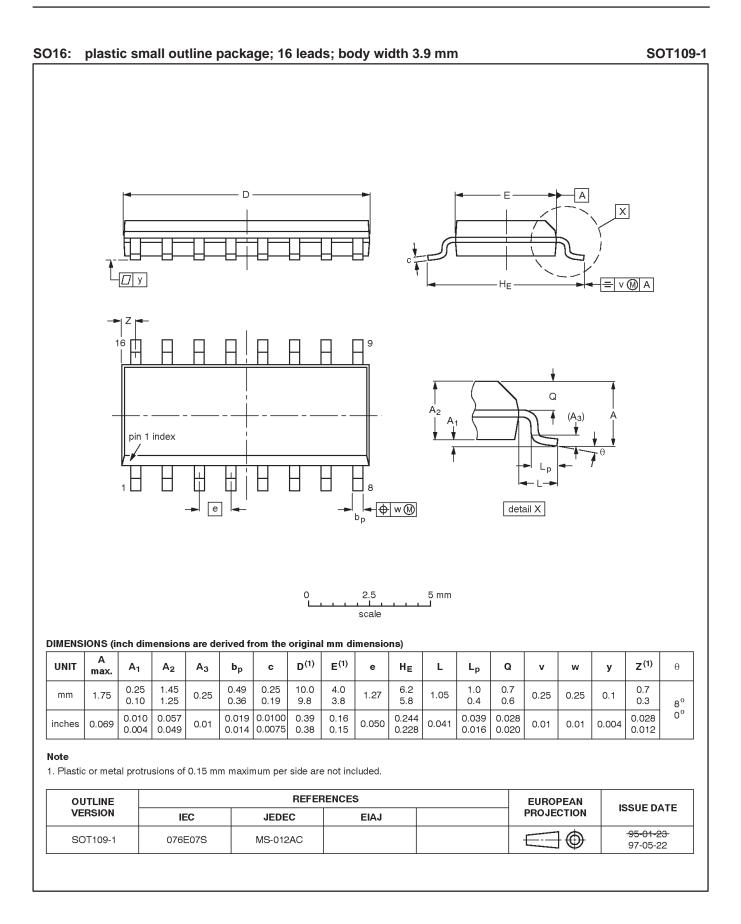
0.01

0.030

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SOT38-4

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